



1.0mm FH (IEEE 1386) Connectors

Photo 105882

Product Facts

- For board stacking applications
- High density packaging on 1.0 [.039] centerline spacing
- Available in standard 64-position and optional 84-position sizes
- "Tape-and-reel" packaged per EIA standards
- Board stacking heights available from 8 [.315] to 15 [.591] (see page 55)
- Increased plastic clearance eliminates stress to solder joints during mating (see page 55)
- Improved locating posts ensure accurate hand or robotic placement (see page 55)
- Meets EIA-700 AAAB specifications for IEEE 1386 applications



As a standard for adding local PCI or Sbus performance to Futurebus+ and VMEbus applications, IEEE 1386 offers new levels of performance and packaging convenience through the mezzanine architecture.

AMP makes it easier and more productive to add an IEEE 1386 mezzanine connector to your system. The surface-mount parallel stacking connector features contacts on a 1.0 [.039] pitch and is available in eight stacking heights from 8 [.315] to 15 [.591]. Sizes include the IEEE 1386 standard 64-position version and an optional 84-position version.

Not only is the connector compatible with EIA-700 AAAB — the connector standard for IEEE 1386 mezzanine connectors — it offers several enhancements that make it easier to use and more reliable.

Increased plastic clearance between mating connectors makes it easier to align multiple connectors for mating, thus eliminating stress to the solder joints during engagement. Improved locating posts allow fast, highly accurate hand placement of connectors. The connectors are available with vacuum covers for automated placement.

Performance Characteristics

Current Rating:

1.0 ampere per contact

Contact Resistance:

30 miliohms max. (initial)

Durability:

tested to 100 mating cycles min.